

Product Change Notice (PCN)

Date: **05/23/2023**

PCN Number: **PCN-0454916R-01**

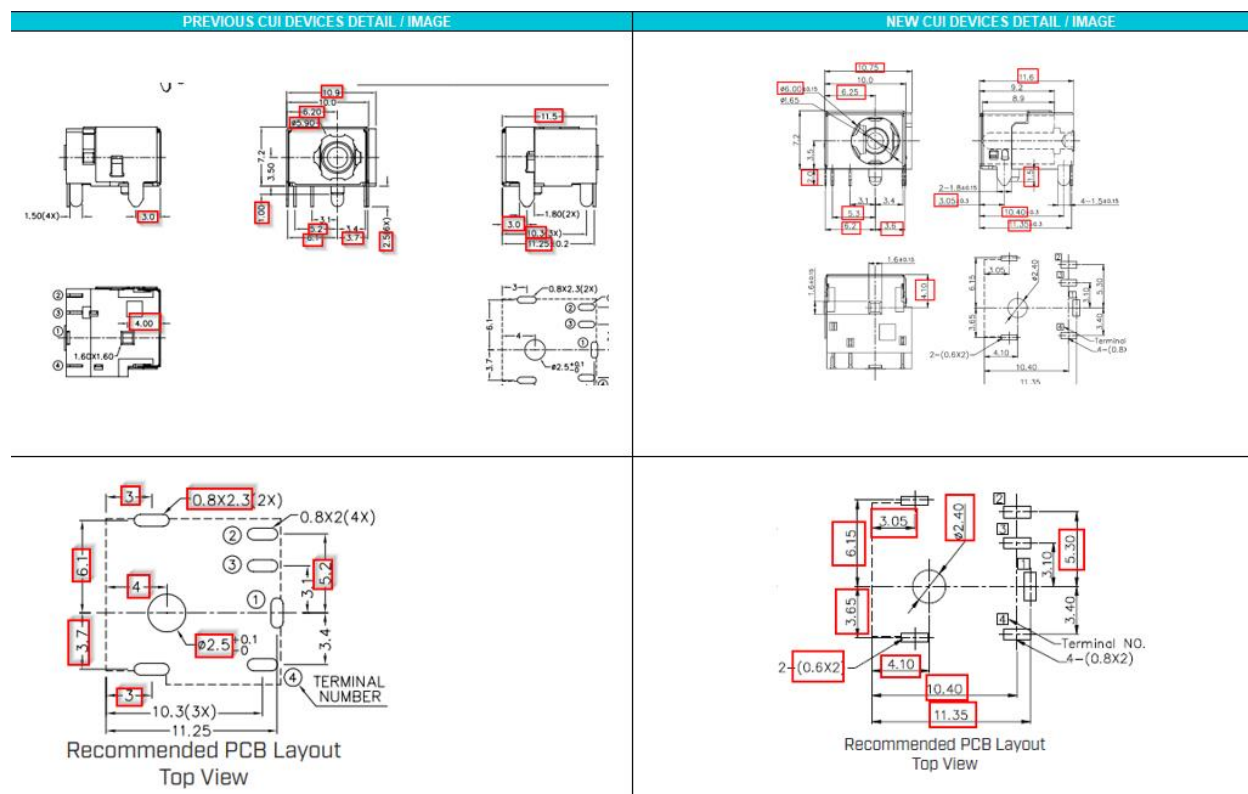
To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

Product(s) Affected: **PJ-085H**

Reason(s) for Change: **Manufacturing process improvements**

Description of Change: **Minor Housing and footprint differences. Material Change on the housing and terminals. See image Below**



F-723-001

Revision: A

PREVIOUS CUI DEVICE'S DETAIL / IMAGE

MATING PLUG
Jack Insertion Depth: 8.2 mm

	MATERIAL	PLATING
center pin	copper	nickel
terminal 1	brass	silver
terminal 2	copper alloy	silver
terminal 3	brass	silver
terminal 4	copper alloy	silver
shield A	brass	nickel
shield B	stainless steel	
insulator	PA10T	

NEW CUI DEVICE'S DETAIL / IMAGE

MATING PLUG
Jack Insertion Depth: 9.2 mm

DESCRIPTION	MATERIAL	PLATING
center pin	brass	nickel
terminal 1	brass	silver
terminal 2	phosphor bronze	silver
terminal 3	brass	silver
terminal 4	phosphor bronze	silver
shield A	brass	nickel
shield B	stainless steel	clean
housing	PA10T (UL94V-0)	black

PREVIOUS CUI DEVICE'S DETAIL / IMAGE

SOLDERABILITY

parameter	conditions/description	min	typ	max	units
real storage	at relative humidity <80%		40		°C
reflow soldering ¹	see reflow profile	255	260	265	°C
drying conditions ²	parts in reel: bake at 40°C ±5°C for 72 hours parts removed from reel: bake at 40°C ±5°C for 10 hours				

Note: 1. It is recommended to reflow solder within 72 hours from opening vacuum packaging at a temperature <30°C & relative humidity <80%.
2. When unsealing from 90 to >10 hours.

NEW CUI DEVICE'S DETAIL / IMAGE

SOLDERABILITY

parameter	conditions/description	min	typ	max	units
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Note: 1. It is recommended to reflow solder within 72 hours from opening vacuum packaging at a temperature <30°C & relative humidity <80%.
2. When unsealing from 90 to >10 hours.



Affected Date Code: 05/19/2023

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality

A handwritten signature in black ink, appearing to read "Robert D. Davis", positioned above a horizontal line.

Product Management

A handwritten signature in black ink, positioned above a horizontal line.